



## **JAPAN INTERNATIONAL COOPERATION AGENCY (JICA) SRI LANKA OFFICE**

### **Consulting Service for Data Collection Survey for Landslide Disaster Risk Reduction in Sri Lanka**

JICA is the implementing agency for Japan's bi-lateral Official Development Assistance (ODA) programmes/projects globally. JICA Sri Lanka Office, established in 1982, has been involved in numerous bi-lateral ODA assistance programmes/projects in various sectors through our main modalities - Japanese ODA Loan, Technical Co-operation and Grant Aid.

Currently we are seeking the Consultant/ Consulting Firm for Data Collection Survey to mainstream Landslide Disaster Risk Reduction in Sri Lanka for considering JICA's future activities in Disaster Risk Reduction Sector.

The Consultant will be responsible for implementation of following tasks;

- **Identify Capacity Gaps**

Identify gaps latent amongst relevant stakeholders in Sri Lanka (NBRO Headquarters, NBRO Regional Offices, and local authorities) related to Landslide Disaster Risk Reduction.

- **Propose a Roadmap**

Based on the identified gaps, develop a Roadmap focus on landslide disaster risk reduction in a proactive manner which includes structural measures and land use control.

Expected Duration: Approximately 2.0 months (December 2024 – March 2025) on Contract basis.

#### **Requirements for the applicants:**

- Good communication and reporting skills in English.
- Educational background in engineering, geology, legal (Governance, law, public policy etc.) or any other relevant disciplines and experience of similar assignment.

Interested applicants are requested to contact the below to obtain detailed TOR and application documents;

- Send the request mail to E-mail address - to :  
**Wickramasinghe-Vindhya@jica.go.jp** with copy to:  
**ThiyagarajahParamendiren.SL@jica.go.jp** and  
**Sakurazawa.Takafumi@jica.go.jp** with title "Request for Proposal - Consulting Service for Data Collection Survey for Landslide Disaster Risk Reduction in Sri Lanka".
- Closing date for the Request: **December 09, 2024.**

Closing date for the submission of application document:  
December 20, 2024.